

500.40053X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):

S. ISHIHARA, et al.

Serial No.:

09/830,127

Filed:

April 24, 2001

For:

MULTILAYER ELECTRONIC PART, ITS MANUFACTURING METHOD, TWO-DIMENSIONALLY ARRAYED ELEMENT PACKAGING STRUCTURE, AND ITS MANUFACTURING

METHOD

Group:

2822

Examiner:

R. Potter

AMENDMENT

Mail Stop - Fee Amendment **Commissioner for Patents** P.O. Box 1450 Alexandria, VA 22313-1450

January 16, 2004

Sir:

In response to the Office Action October 16, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application, as listed below and as set forth on the following pages:

Amendment of the Claims; and

Remarks are included following the amendments.

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